



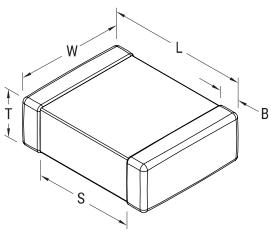
Dimensions Chip Size

W T

S

В

SMD Comm X8G HT150C, Ceramic, 750 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



Click here for the 3D model.			SI
			Μ
			S
	1210		С
	3.2mm +/-0.2mm		М
	2.5mm +/-0.2mm		To

0.78mm +/-0.10mm

0.5mm +/-0.25mm

1.5mm MIN

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	750 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	20%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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